

Synamic 8G

PROPERTY	Typical Value	Unit	Condition	Test Method
Glass Transition Temperature, Tg	200	°C	A	DMA IPC-TM-650 2.4.24.2
Glass Transition Temperature, Tg	190	°C	A	DSC IPC-TM-650 2.4.25
Thermal Expansion, Z CTE	48	ppm/°C	A	Before Tg, IPC-TM-650 2.4.24
Thermal Expansion, Z CTE	180	ppm/°C	A	After Tg, IPC-TM-650 2.4.24
Decomposition Temperature, Td	430	°C	A	TMA IPC-TM650 2.4.24.6
Delamination Time, T288	60	minutes	A	TMA IPC-TM650 2.4.24
Delamination Time, T300	60	minutes	A	TMA IPC-TM650 2.4.24
Humidity Resistance	>10	cycles	85°C/85%RH/168 Hours 288°C/10sec Dipping	-
Dielectric Constant (Dk)	3.73	-	1 GHz	IPC-TM-650 2.5.5.9
Dielectric Constant (Dk)	3.68	-	10 GHz	IPC-TM-650 2.5.5.5
Dissipation Factor (Df)	0.0015	-	1 GHz	IPC-TM-650 2.5.5.9
Dissipation Factor (Df)	0.0032	-	10 GHz	IPC-TM-650 2.5.5.5
Volume Resistivity	1.15×10 ⁸	MΩ·cm	COND A	IPC-TM-650 2.5.17.1
Surface Resistivity	1.55×10 ⁶	MΩ	COND A	IPC-TM-650 2.5.17.1
Electrical Strength	38.5	kV/mm	0.51mm (0.020")	IPC-TM-650 2.5.6.2
Thermal Conductivity	0.61	W/m·K	100	ASTM D5470
Water Absorption	0.08	%	D-24/23	IPC-TM-650 2.6.2.1
Copper Peel Strength	0.75 [4.3]	N/mm [lb/in.]	after solder float 1 oz. HVLP Foil	IPC-TM-650 2.4.8
Flammability	94V-0	-	A	UL